

1. A piezoelectric device having a structure in which a piezoelectric resonator element is bonded to electrodes provided on a package base, comprising:
silicone-based conductive adhesives;

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placing the piezoelectric resonator element on the anchor member provided with a silicone-based conductive adhesive thereon so as to be bonded to the anchor member.

6. The method for manufacturing a piezoelectric device according to
5 Claim 5, the adhering step including adhering conductive adhesive to the jig that is at
least one of an epoxy-based and a polyimide-based conductive adhesive.

7. The method for manufacturing a piezoelectric device according to Claim 4, the moving step including moving a jig that is a stamping jig.